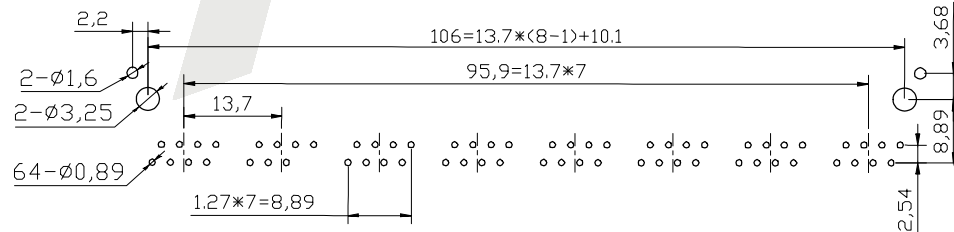
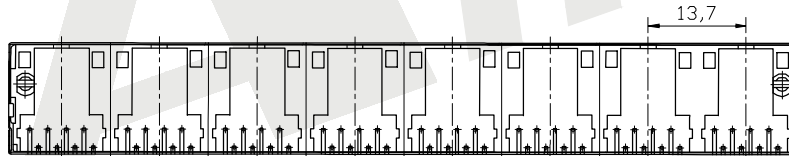
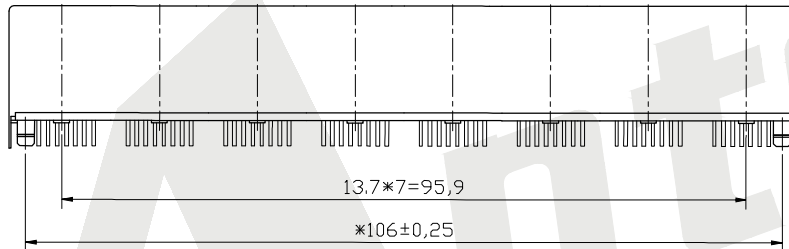
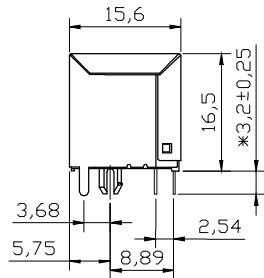
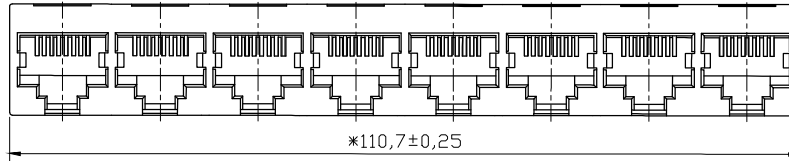


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1 μ ~ 50 μ "OVER NICKEL IN CONTACT AREA. 150 μ " TIN PLATIN. OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mm THICKNESS COPPER WITH NICKEL PLATE I

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30 MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVRONMENTAL

- 1. STORAGE : -40° C TO 85° C
- 2. OPERATION : 0° C TO 70° C

Order code:

ATRJ5222 - 8P - 8C - X - D - F

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
 - ② NUMBER OF POSITIONS (8P, 6P, 4P)
 - ③ NUMBER OF CONTACTS (8C, 6C, 4C)
 - ④ Contact Plating
 - ⑤ Shield
 - ⑥ Ports
- A:W/O Shield
 - B:Half Shield
 - C:Shield W/Eml
 - D:Shield W/O Eml
 - A:1X1P
 - B:1X2P
 - C:1X4P
 - D:1X5P
 - E:1X6P
 - F:1X8P
- G0:Gold flash
 - G1: 3U" Gold
 - G2: 5U" Gold
 - G3:10U" Gold
 - G4:15U" Gold
 - G5:30U" Gold
 - SN:Tin

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

Antenk ANTEK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 30/07/2019
CHECK BobYang DATE 30/07/2019

TITLE: Modular Jack Top entry
8P8C, 1X8Port Full shielded



DRAWING NO: ATRJ5222-8P8C-X-D-F
PRODUCT NO: ATRJ5222-8P8C-X-D-F

REV	DESCRIPTION	DATE

1 2 3 4 5 6 7 8